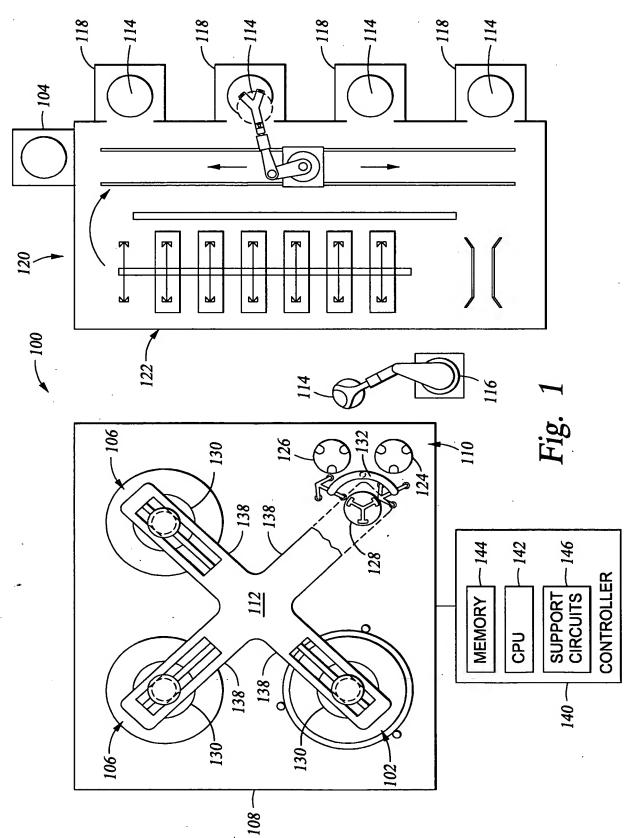
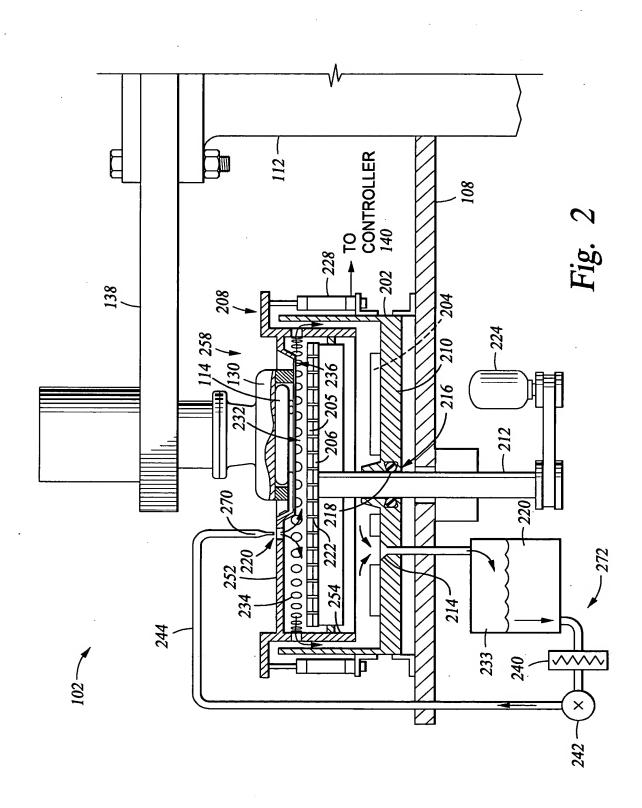
Atty Dkt. No. . . AMAT/5844/CMP/CMP/RK/ U.S. Serial No. UNKNOWN Filed: HEREWITH Applicant: APPLIED MATERIALS, INC. Inventor: LIAN-YUH CHEN, ET AL. Express Mail No.: EV041916445US Page 1 of 16

 $\neg$ 



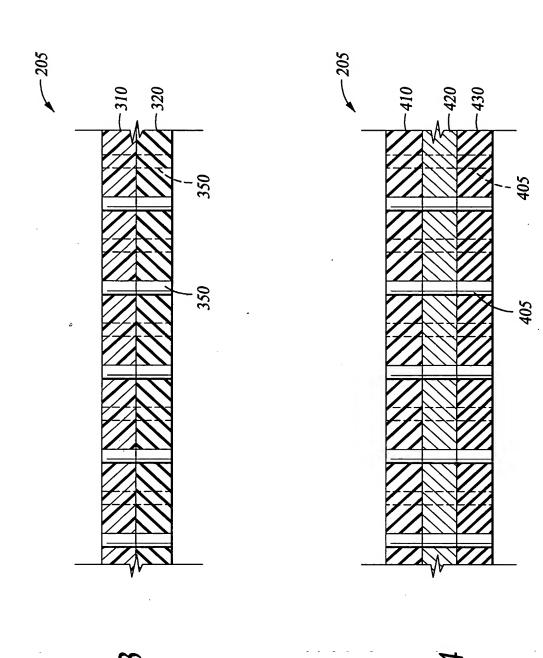


Atty Dkt. No. AMAT/5844/CMP/CMP/RKK U.S. Serial No. UNKNOWN Filed: HEREWITH Applicant: APPLIEDMATERIALS, INC. Inventor: LIAN-YUH CHEN, ET AL. Express Mail No.: EV041916445US Page 2 of 16



Atty Dkt. No. AMAT/5844/CMP/CMP/RKK U.S. Serial No. UNKNOWN Filed: HEREWITH Applicant: APPLIEDMATERIALS, INC. Inventor: LIAN-YUH CHEN, ET AL. Express Mail No.: EV041916445US Page 3 of 16

3/16



Atty Dkt. No. AMAT/5844/CMP/CMP/RKK U.S. Serial No. UNKNOWN Filed: HEREWITH Applicant: APPLIEDMATERIALS, INC. Inventor: LIAN-YUH CHEN, ET AL. Express Mail No.: EV041916445US

Page 4 of 16

4/16

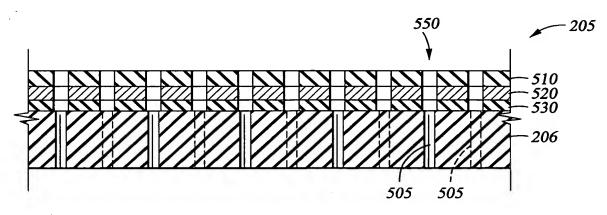


Fig. 5A

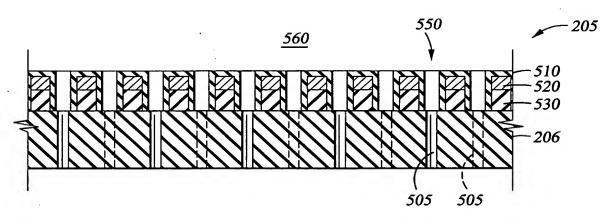


Fig. 5B

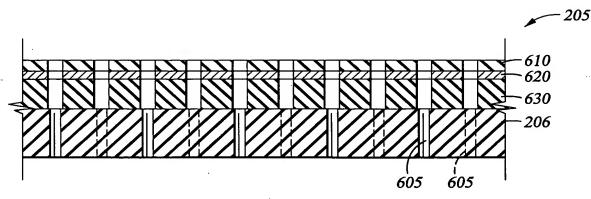


Fig. 6

Atty Dkt. No. U.S. Serial No.

AMAT/5844/CMP/CMP/RKK UNKNOWN

O.S. Serial NO.
Filed:
Applicant:
Inventor:
Express Mail No.: EV041916445US
Page 5 of 16 APPLIEDMATERIALS, INC.

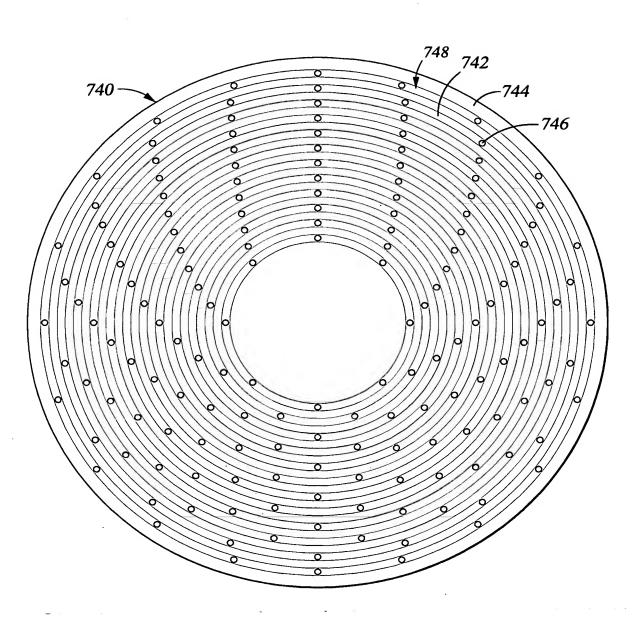


Fig. 7

Atty Dkt. No. AMAT/5844/CMP/CMP/RKK U.S. Serial No. UNKNOWN Filed: HEREWITH Applicant: APPLIEDMATERIALS, INC. LIAN-YUH CHEN, ET AL. Express Mail No.: EV041916445US

Page 6 of 16

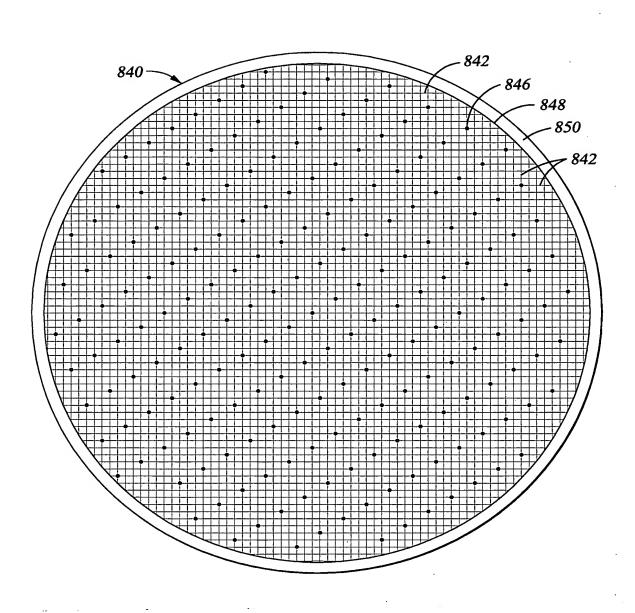


Fig. 8

Atty Dkt. No. AMAT/5844/CMP/CMP/RKK U.S. Serial No. UNKNOWN Filed: HEREWITH Applicant: APPLIEDMATERIALS, INC. Inventor: LIAN-YUH CHEN, ET AL. Express Mail No.: EV041916445US Page 7 of 16

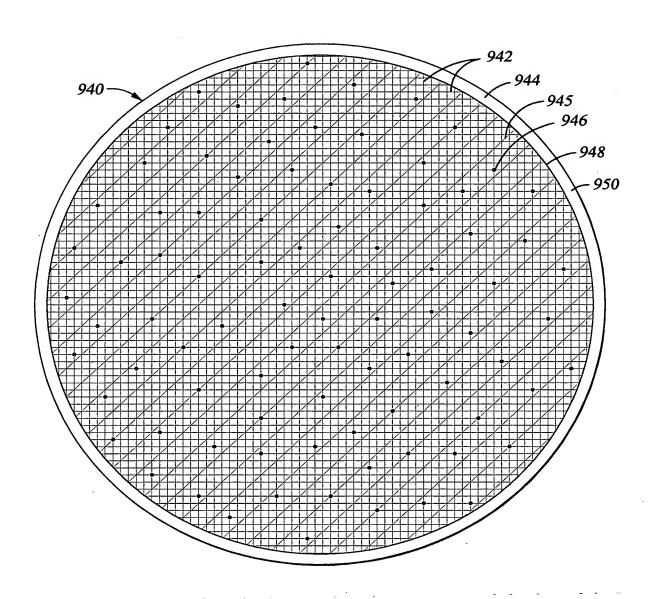
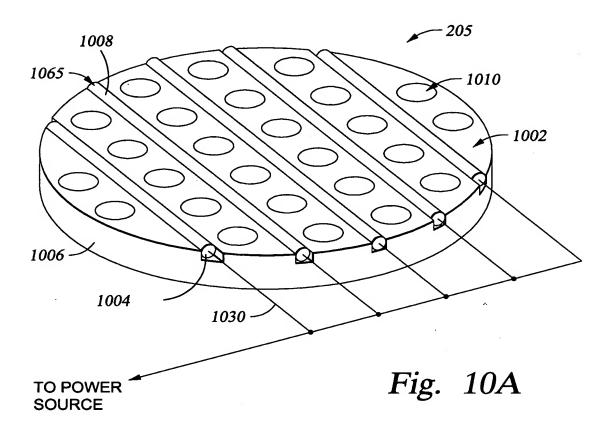
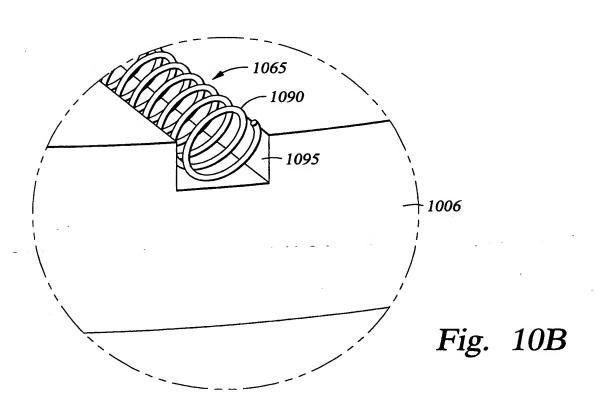


Fig. 9

Atty Dkt. No.
U.S. Serial No.
Filed:
Applicant:
Inventor:
Express Mail No.: EV041916445US
Page 8 of 16

Page 8 of 16

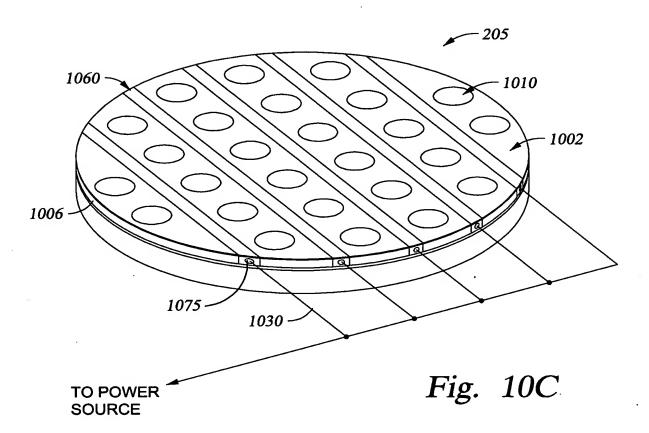


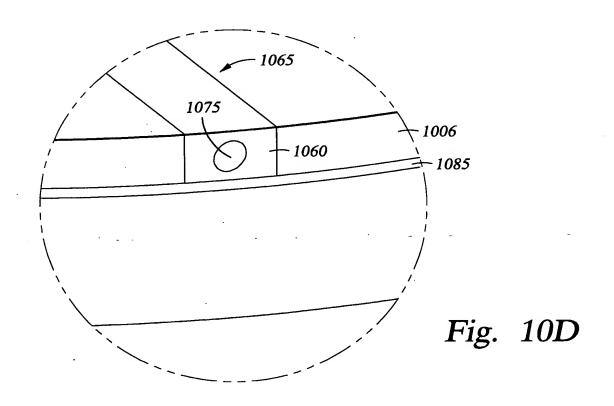


Atty Dkt. No. U.S. Serial No. Filed: AMAT/5844/CMP/CMP/RKK UNKNOWN

Filed: Applicant: Inventor: HEREWITH
APPLIEDMATERIALS, INC.
LIAN-YUH CHEN, ET AL.

Express Mail No.: EV041916445US Page 9 of 16





 $oldsymbol{ol}}}}}}}}}}}}}$ 

Atty Dkt. No. AMAT/5844/CMP/CMP/RKK U.S. Serial No. UNKNOWN Filed: HEREWITH Applicant: APPLIEDMATERIALS, INC. Inventor: LIAN-YUH CHEN, ET AL. Express Mail No.: EV041916445US Page 10 of 16

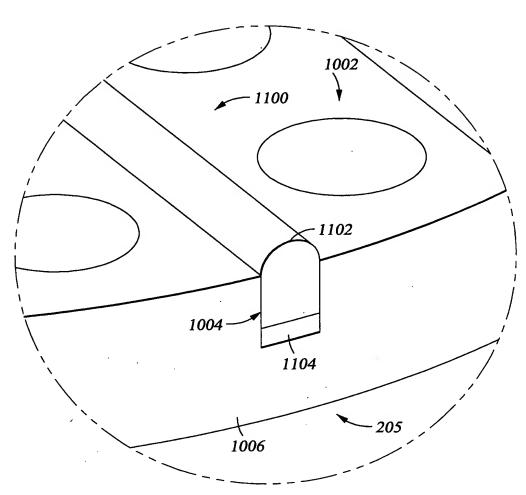
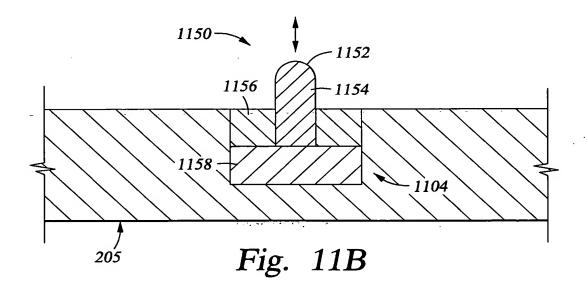
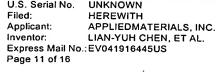


Fig. 11A

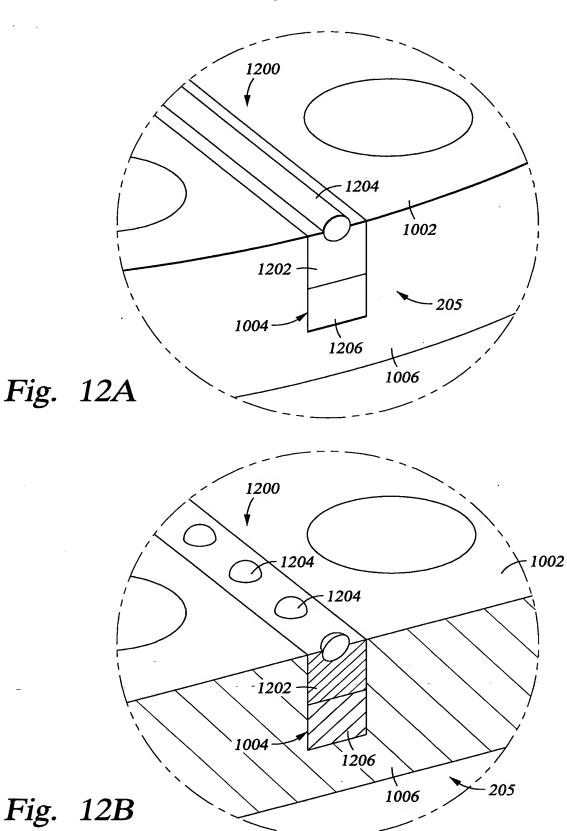


Atty Dkt. No. U.S. Serial No. AMAT/5844/CMP/CMP/RKK UNKNOWN



 $\neg$ 

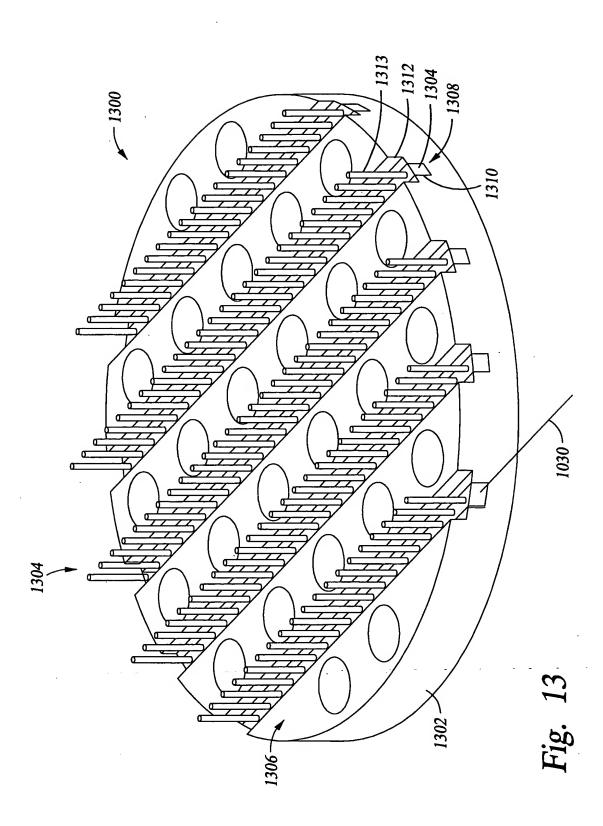
11/16



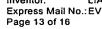
Atty Dkt. No. U.S. Serial No. Filed:

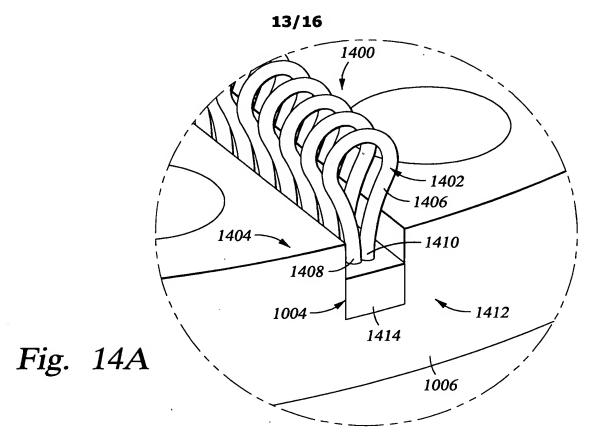
AMAT/5844/CMP/CMP/RKK UNKNOWN

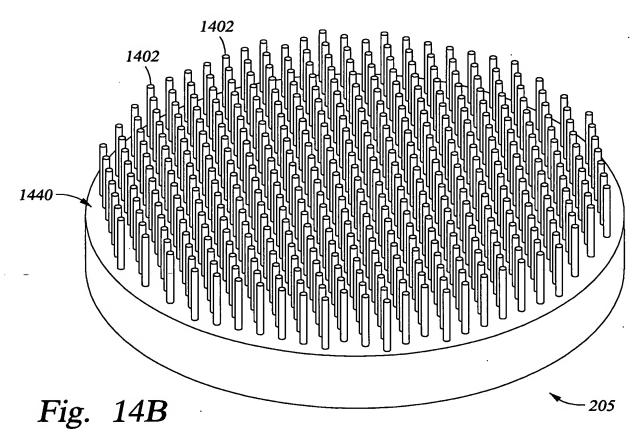
Filed: UNKNOWN
Applicant: APPLIEDMATERIALS, INC. Inventor: LIAN-YUH CHEN, ET AL. Express Mail No.: EV041916445US
Page 12 of 16



Atty Dkt. No. AMAT/5844/CMP/CMP/RKK U.S. Serial No. UNKNOWN Filed: HEREWITH Applicant: APPLIEDMATERIALS, INC. Inventor: LIAN-YUH CHEN, ET AL. Express Mail No.: EV041916445US

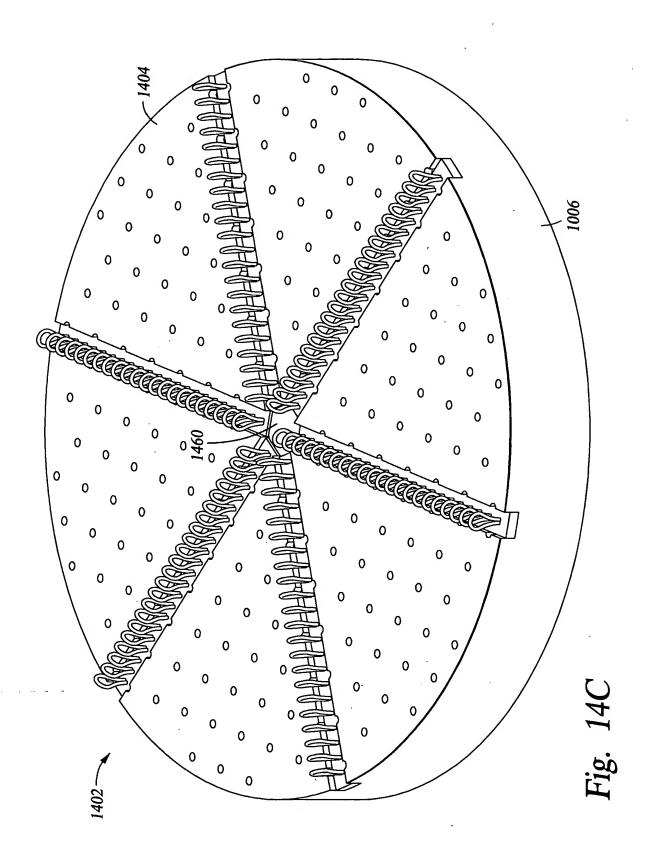






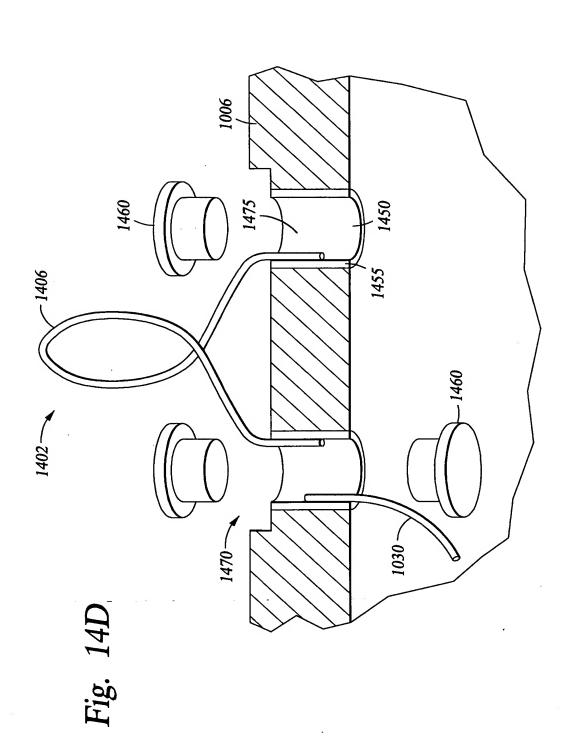
Atty Dkt. No. U.S. Serial No.

AMAT/5844/CMP/CMP/RKK UNKNOWN HEREWITH Applicant: APPLIEDMATERIALS, INC. Inventor: LIAN-YUH CHEN, ET AL. Express Mail No.: EV041916445US
Page 14 of 16



Atty Dkt. No. AMAT/5844/CMP/CMP/RKK U.S. Serial No. UNKNOWN Filed: HEREWITH Applicant: APPLIEDMATERIALS, INC. Inventor: LIAN-YUH CHEN, ET AL. Express Mail No.: EV041916445US Page 15 of 16

15/16





Atty Dkt. No. U.S. Serial No. Filed:

Applicant:

AMAT/5844/CMP/CMP/RKK UNKNOWN

HEREWITH APPLIEDMATERIALS, INC. LIAN-YUH CHEN, ET AL.

Inventor: LIAN-YUH CHEN Express Mail No.: EV041916445US

Page 16 of 16





Fig. 15A

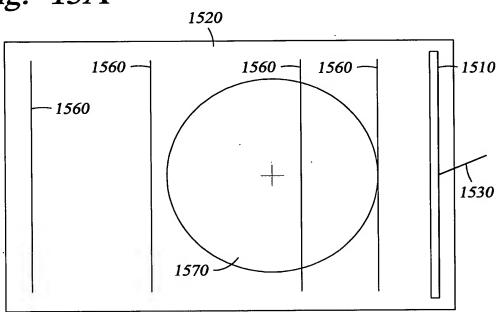


Fig. 15B

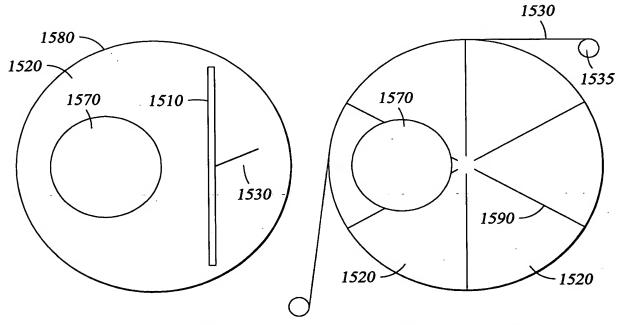


Fig. 15C

Fig. 15D

- 1550